- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
 - ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

These quadruple 2-line to 1-line data selectors/multiplexers are designed for 2-V to 5.5-V V_{CC} operation.

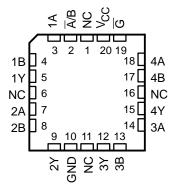
The 'AHC158 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. These devices provide inverted data.

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SN54AHC158 J OR W PACKAGE
SN74AHC158D, DB, DGV, N, NS, OR PW PACKAGE

(10	P VI	EW)
А/в [1	Ο	16	<u>V</u> cc
1A [2		15	IJG
1B [3		14] 4A
1Y [4		13] 4B
2A [5		12] 4B] 4Y
2B [6		11	3A
2Y [7		10] 3B
GND [8		9] 3Y

SN54AHC158 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

т _А	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING				
	PDIP – N	Tube	SN74AHC158N	SN74AHC158N				
	SOIC – D	Tube	SN74AHC158D	AHC158				
	3010 - 0	Tape and reel	SN74AHC158DR	ALICI36				
–40°C to 85°C	SOP – NS Tape and		SN74AHC158NSR	AHC158				
-40 C 10 05 C	SSOP – DB	Tape and reel	SN74AHC158DBR	HA158				
	TSSOP – PW	Tube	SN74AHC158PW	HA158				
	1330F - FW	Tape and reel	SN74AHC158PWR	11A150				
	TVSOP – DGV	Tape and reel	SN74AHC158DGVR	HA158				
	CDIP – J	Tube	SNJ54AHC158J	SNJ54AHC158J				
–55°C to 125°C	CFP – W	Tube	SNJ54AHC158W	SNJ54AHC158W				
	LCCC – FK	Tube	SNJ54AHC158FK	SNJ54AHC158FK				

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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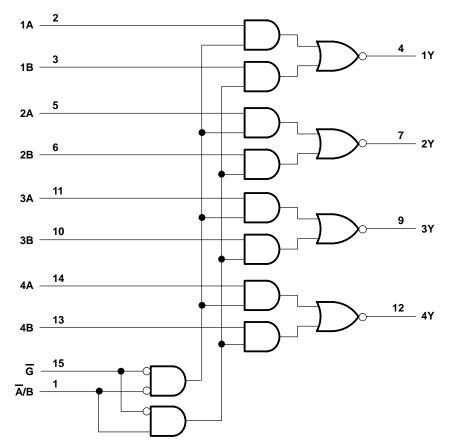


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(FUNCTION TABLE (each data selector/multiplexer)						
	INPU	JTS		OUTPUT			
G	A/B	Α	В	Y			
Н	Х	Х	Х	Н			
L	L	L	Х	н			
L	L	Н	Х	L			
L	Н	Х	L	н			
L	Н	Х	Н	L			

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range, V _I (see Note 1) Output voltage range, V _O (see Note 1) Input clamp current, I _{IK} (V _I < 0) Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) Continuous output current, I _O (V _O = 0 to V _{CC}) Continuous current through V _{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): D	-0.5 V to 7 V -0.5 V to 7 V -0.5 V to 7 V -0.5 V to V _{CC} + 0.5 V -20 mA ±20 mA ±20 mA ±25 mA ±50 mA D package 73°C/W DB package 82°C/W DGV package 67°C/W N package 64°C/W PW package 108°C/W
	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54A	HC158	SN74A	HC158	UNIT	
			MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
VIH	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85			
		$V_{CC} = 2 V$		0.5		0.5		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9	V	
		V _{CC} = 5.5 V		1.65		1.65		
VI	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0 <	Vcc	0	VCC	V	
		$V_{CC} = 2 V$	(c)	-50		-50	μA	
IOH	High-level output current	V_{CC} = 3.3 V ± 0.3 V	na l	-4		-4	mA	
		V_{CC} = 5 V ± 0.5 V	40	-8		-8	ma	
		V _{CC} = 2 V		50		50	μΑ	
IOL	Low-level output current	V_{CC} = 3.3 V ± 0.3 V		4		4	mA	
		V_{CC} = 5 V ± 0.5 V		8		8	ma	
A+/A.v	logut transition rise or fell rate	V_{CC} = 3.3 V ± 0.3 V		100		100	ns/V	
Δt/Δv	Input transition rise or fall rate	V_{CC} = 5 V ± 0.5 V		20		20	115/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	N	Τį	λ = 25°C	;	SN54AH	IC158	SN74AI	HC158	
PA	RAMEIER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	2		1.9		1.9		
		I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9		
VOH			4.5 V	4.4	4.5		4.4		4.4		V
		I _{OH} = -4 mA	3 V	2.58			2.48	M:	2.48		
		I _{OH} = -8 mA	4.5 V	3.94			3.8	-M	3.8		
			2 V			0.1	0	0.1		0.1	
		I _{OL} = 50 μA	3 V			0.1	07	0.1		0.1	
VOL			4.5 V			0.1	n_Q	0.1		0.1	V
		I _{OL} = 4 mA	3 V			0.36	PPC	0.5		0.44	
		I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
lj	A or B inputs	VI = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40		40	μA
Ci		V _I = V _{CC} or GND	5 V		2	10				10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 V$.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	Δ = 25 °	C	SN54A	HC158	SN74A	HC158	UNIT			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT			
^t PLH	A or B	Y	Ci - 15 pE		6.2**	9.7**	1**	11.5**	1	11.5				
^t PHL	AUB	I	C _L = 15 pF		6.2**	9.7**	1**	11.5**	1	11.5	ns			
^t PLH	Ā/B	Y	Ci - 15 pE		8.4**	13.2**	1**	15.5**	1	15.5	ns			
^t PHL	A/B	T	C _L = 15 pF		8.4**	13.2**	1**	15.5**	1	15.5	115			
^t PLH	0	Y	C _I = 15 pF		8.7**	13.6**	1**	16**	1	16	ns			
^t PHL	9	•		0L = 13 pi	0 <u></u> - 10 pi			8.7**	13.6**	1**	16**	1	16	110
^t PLH	A or B	Y	$C_{\rm L} = 50 \rm pE$		8.7	13.2	1	Q 15	1	15				
^t PHL	AOIB	Ť	C _L = 50 pF		8.7	13.2	15	15	1	15	ns			
^t PLH	Ā/B	Y	C _I = 50 pF		10.9	16.7	3	19	1	19	ns			
^t PHL	A/B	r	CL = 50 pr		10.9	16.7	a 1	19	1	19	115			
^t PLH	G	Y	C _I = 50 pF		11.2	17.1	1	19.5	1	19.5	ns			
^t PHL	G	ſ	CL = 50 pF		11.2	17.1	1	19.5	1	19.5	115			

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	Τį	ן = 25°C	;	SN54A	HC158	SN74A	HC158	UNIT				
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT				
^t PLH	A or B	Y	Ci = 15 pE		4.1*	6.4*	1*	7.5*	1	7.5					
^t PHL	AULP	r	C _L = 15 pF		4.1*	6.4*	1*	7.5*	1	7.5	ns				
^t PLH	Ā/B	Y	Ci - 15 pE		5.3*	8.1*	1*	9.5*	1	9.5					
^t PHL	A/B	Ť	C _L = 15 pF		5.3*	8.1*	1*	9.5*	1	9.5	ns				
^t PLH	IJ	Y	0. 15 pF		5.6*	8.6*	1*	10*	1	10					
^t PHL	G	r	I	Ι	1	1	C _L = 15 pF		5.6*	8.6*	1*	¥10*	1	10	ns
^t PLH	A or B	Y	$C_{\rm L} = 50 \rm pE$		5.6	8.4	1	9.5	1	9.5	ns				
^t PHL	AUB	I	C _L = 50 pF		5.6	8.4	20	9.5	1	9.5	115				
^t PLH	Ā/B	Y	C _I = 50 pF		6.8	10.1	5	11.5	1	11.5					
^t PLH	A/B	ſ	CL = 50 pF		6.8	10.1	Q 1	11.5	1	11.5	ns				
^t PLH	G	Y	$C_{1} = 50 \text{ pF}$		7.1	10.6	1	12	1	12	ns				
^t PHL	G	ř	C _L = 50 pF		7.1	10.6	1	12	1	12	115				

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER		SN74AHC158			
	PARAMETER				UNIT	
VOL(P)	Quiet output, maximum dynamic V _{OL}			0.8	V	
VOL(V)	Quiet output, minimum dynamic V _{OL}			-0.8	V	
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.8		V	
VIH(D)	High-level dynamic input voltage	3.5			V	
V _{IL(D)}	Low-level dynamic input voltage			1.5	V	

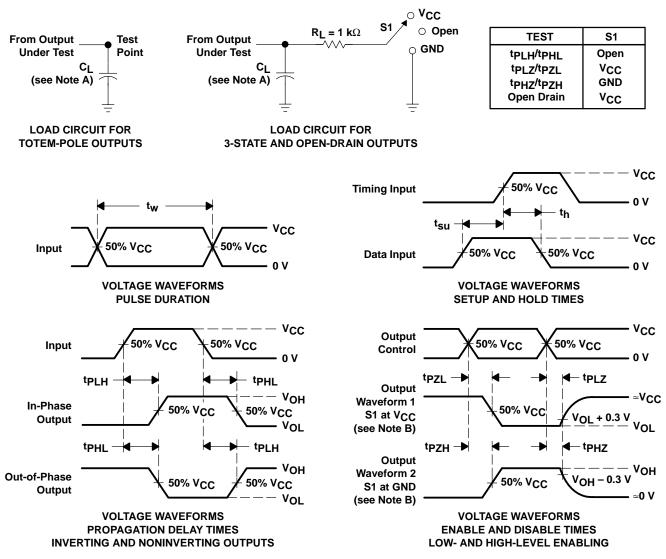
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load,	f = 1 MHz	11	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHC158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI
SN74AHC158DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DGVRG4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC158NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC158NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74AHC158PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC158PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

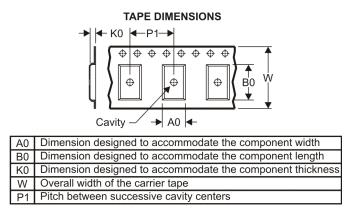
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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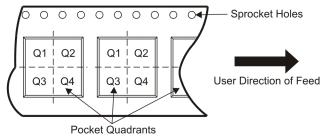
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

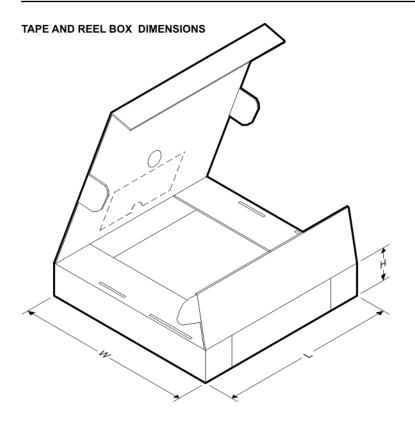


Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC158DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AHC158DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHC158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHC158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHC158PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC158DBR	SSOP	DB	16	2000	346.0	346.0	33.0
SN74AHC158DGVR	TVSOP	DGV	16	2000	346.0	346.0	29.0
SN74AHC158DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AHC158NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74AHC158PWR	TSSOP	PW	16	2000	346.0	346.0	29.0

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

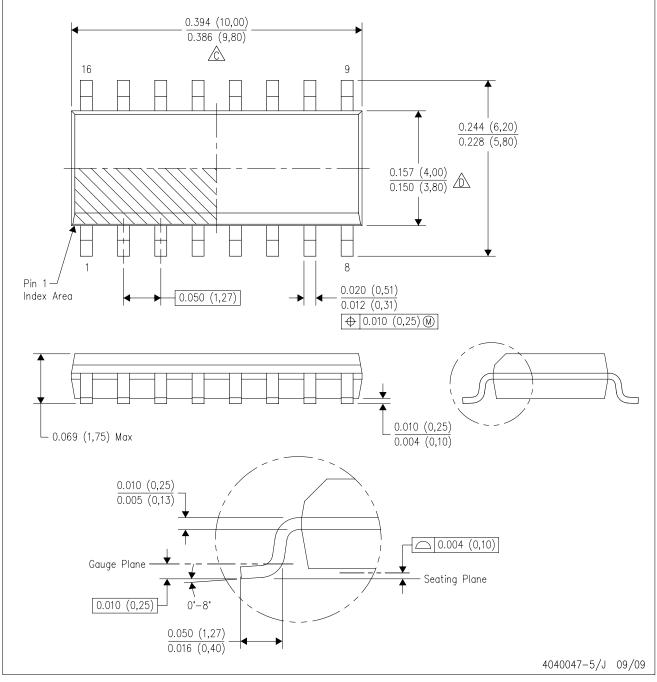
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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